

HVC190

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0441-0100 (Previous: ADE-208-1595) Rev.1.00 Dec 22, 2004

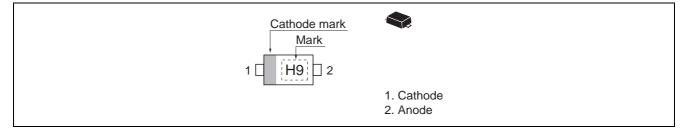
Features

- Low capacitance. (C = 0.35 pF max)
- Low forward resistance. ($rf = 3.0 \Omega typ$)
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC190	H9	UFP

Pin Arrangement





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol Value		Unit
Reverse voltage	V _R	50	V
Forward current	rd current I _F 50		mA
Power dissipation	Pd	150	mW
Junction temperature	Тј	125	٥°
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

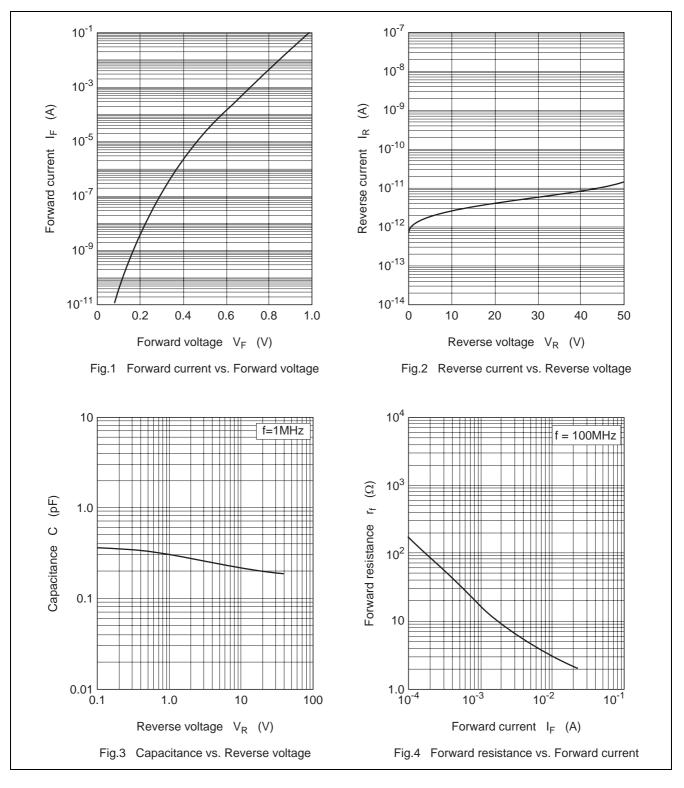
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Мах	Unit	Test Condition
Forward voltage	V _F	—	—	1.0	V	I _F = 50 mA
Reverse current	I _R	—	—	100	nA	V _R = 50 V
Capacitance	С	—	—	0.35	pF	V _R = 50 V, f = 1 MHz
Forward resistance	r _f	_	3.0	5.0	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability * ¹		200			V	C = 200 pF, Both forward and reverse direction 1 pulse

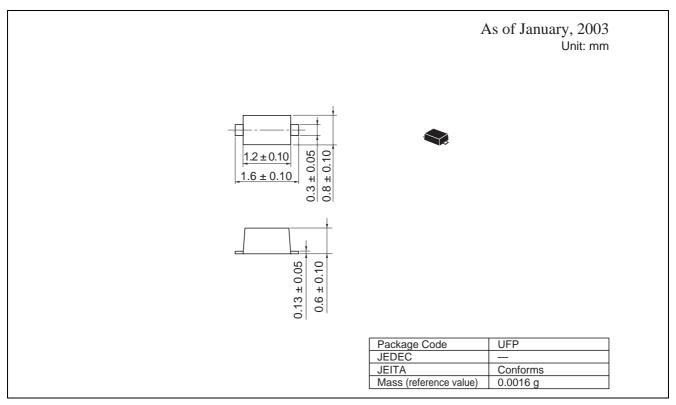
Note: 1. Failure criterion ; $I_R \ge 200$ nA at V_R = 50 V



Main Characteristic



Package Dimensions





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